

Title (en)

ALUMINIUM-COPPER CONNECTOR HAVING A HETEROSTRUCTURE, AND METHOD FOR PRODUCING THE HETEROSTRUCTURE

Title (de)

ALUMINIUM-KUPFER-KONNEKTOR AUFWEISEND EINE HETEROSTRUKTUR UND VERFAHREN ZUR HERSTELLUNG DER HETEROSTRUKTUR

Title (fr)

CONNECTEUR EN ALUMINIUM-CUIVRE COMPRENANT UNE HÉTÉROSTRUCTURE ET PROCÉDÉ DE FABRICATION DE LA HÉTÉROSTRUCTURE

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Application

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Abstract (en)

[origin: WO2018019321A1] The invention relates to a heterostructure comprising at least one first surface containing only copper and at least one second surface, opposite the first surface, containing only aluminium or an aluminium alloy with solid solutions present in the alloy, wherein a. an anchoring layer is arranged between the first and second surfaces, wherein b. each slice plane running perpendicular to the anchoring layer has at least one aluminium or aluminium-alloy island surrounded by copper, and c. at most the aluminium alloy solid solutions which are present in the alloy occur in the anchoring layer. The invention also relates to an aluminium-copper connector and to a heterostructure production method.

IPC 8 full level

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Citation (search report)

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